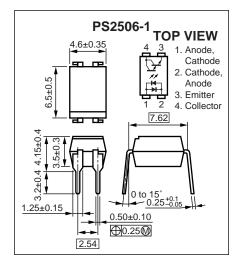
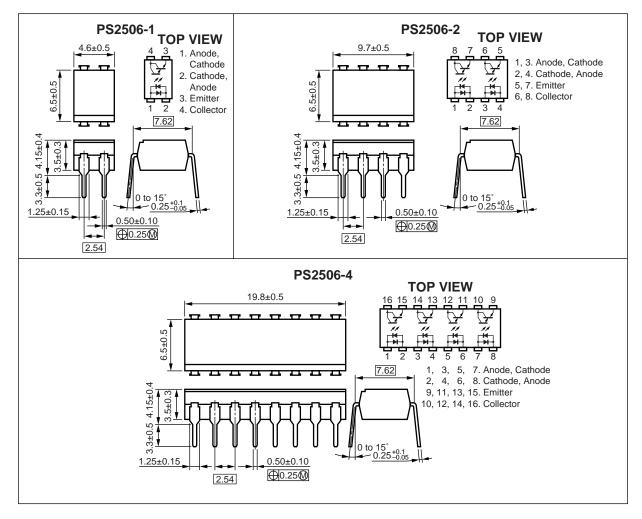
# PACKAGE DIMENSIONS (UNIT : mm)

# DIP Type (New package)



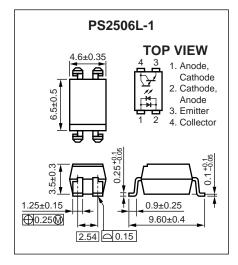
#### Caution New package 1-ch only

## **DIP Type**



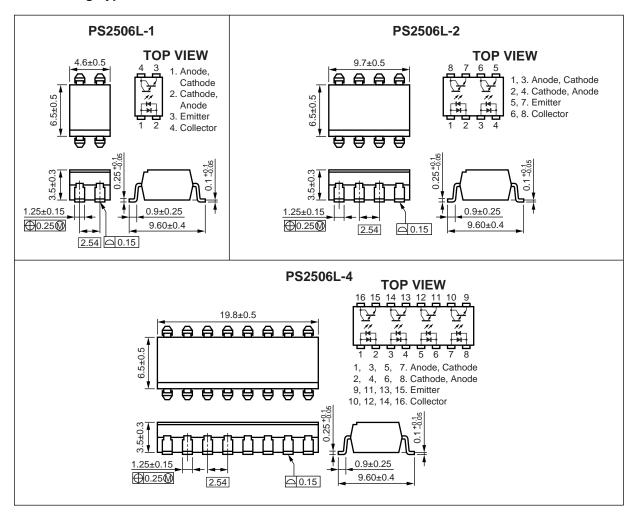
2

# Lead Bending Type (New package)

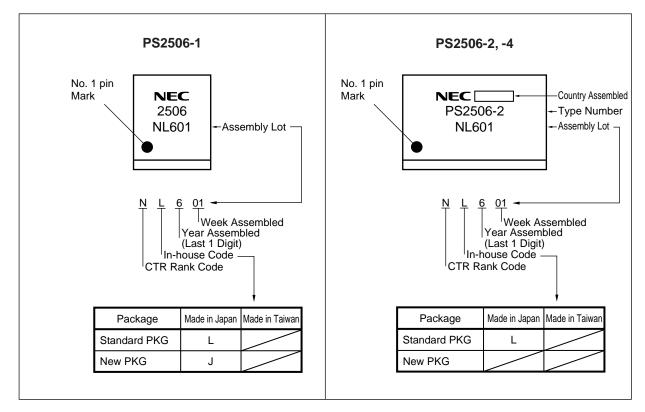


#### Caution New package 1-ch only

#### Lead Bending Type



## **\*** MARKING EXAMPLE



Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number <sup>*1</sup>
PS2506-1	PS2506-1-A	Pb-Free	Magazine case 100 pcs	Standard products	PS2506-1
PS2506L-1	PS2506L-1-A			(UL Approved)	
PS2506L-1-E3	PS2506L-1-E3-A		Embossed Tape 1 000 pcs/reel		
PS2506L-1-E4	PS2506L-1-E4-A				
PS2506L-1-F3	PS2506L-1-F3-A		Embossed Tape 2 000 pcs/reel		
PS2506L-1-F4	PS2506L-1-F4-A				
PS2506-2	PS2506-2-A		Magazine case 45 pcs		PS2506-2
PS2506L-2	PS2506L-2-A				
PS2506L-2-E3	PS2506L-2-E3-A		Embossed Tape 1 000 pcs/reel		
PS2506L-2-E4	PS2506L-2-E4-A				
PS2506-4	PS2506-4-A		Magazine case 20 pcs		PS2506-4
PS2506L-4	PS2506L-4-A				

## ★ ORDERING INFORMATION

\*1 For the application of the Safety Standard, following part number should be used.

## ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings		Unit
			PS2506-1, PS2506L-1	PS2506-2,-4 PS2506L-2,-4	
Diode	Forward Current (DC)	lF	±80		mA/ch
	Power Dissipation Derating	⊿P₀/°C	1.5	1.2	mW/°C
	Power Dissipation	P⊳	150	120	mW/ch
	Peak Forward Current <sup>*1</sup>	<b>I</b> FP	±1		A/ch
Transistor	Collector to Emitter Voltage	Vceo	40		V
	Emitter to Collector Voltage	Veco	6		V
	Collector Current	lc	200	160	mA/ch
	Power Dissipation Derating	⊿Pc/°C	2.0	1.6	mW/°C
	Power Dissipation	Pc	200	160	mW/ch
Isolation Voltage <sup>*2</sup>		BV	5 000		Vr.m.s.
Operating Ambient Temperature		TA	–55 to +100		°C
Storage Temperature		Tstg	–55 to +150		°C

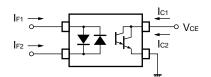
\*1 PW = 100 µs, Duty Cycle = 1%

\*2 AC voltage for 1 minute at T<sub>A</sub> = 25°C, RH = 60% between input and output Pins 1-2 shorted together, 3-4 shorted together (PS2506-1, PS2506L-1).
Pins 1-4 shorted together, 5-8 shorted together (PS2506-2, PS2506L-2).
Pins 1-8 shorted together, 9-16 shorted together (PS2506-4, PS2506L-4).

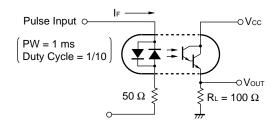
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = ±10 mA		1.17	1.4	V
	Terminal Capacitance	Ct	V = 0 V, f = 1.0 MHz		100		pF
Transistor	Collector to Emitter Dark Current	ICEO	Vce = 40 V, IF = 0 mA			400	nA
Coupled	Current Transfer Ratio (Ic/IF)	CTR	IF = ±1 mA, VcE = 2 V	200	2 000		%
	CTR Ratio <sup>*1</sup>	CTR1/ CTR2	IF = 1 mA, VCE = 2 V	0.3	1.0	3.0	
	Collector Saturation Voltage	VCE(sat)	IF = ±1 mA, Ic = 2 mA			1.0	V
	Isolation Resistance	Ri-o	VI-O = 1.0 kVDC	10 <sup>11</sup>			Ω
	Isolation Capacitance	CI-O	V = 0 V, f = 1.0 MHz		0.5		pF
	Rise Time <sup>*2</sup>	tr	Vcc = 10 V, Ic = 2 mA, R∟ = 100 Ω		100		μS
	Fall Time <sup>*2</sup>	tr			100		

# ELECTRICAL CHARACTERISTICS (TA = 25 °C)

\*1 CTR1 = Ic1/IF1, CTR2 = Ic2/IF2



\*2 Test circuit for switching time



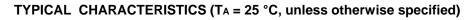
TRANSISTOR POWER DISSIPATION

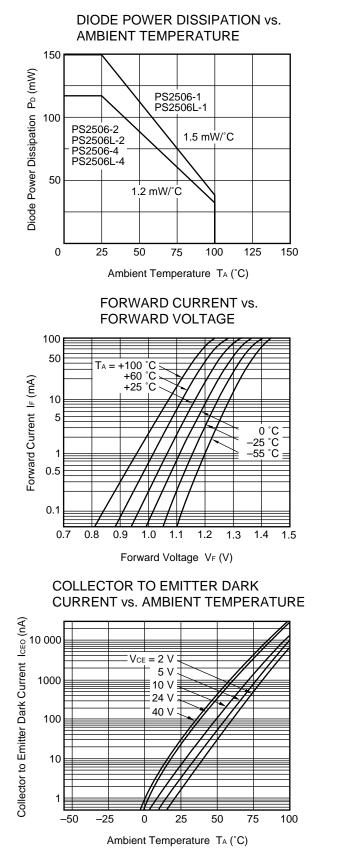
PS2506-1 PS2506L-1

vs. AMBIENT TEMPERATURE

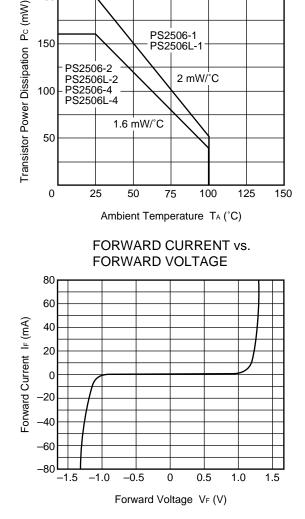
200

150

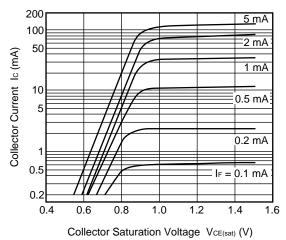


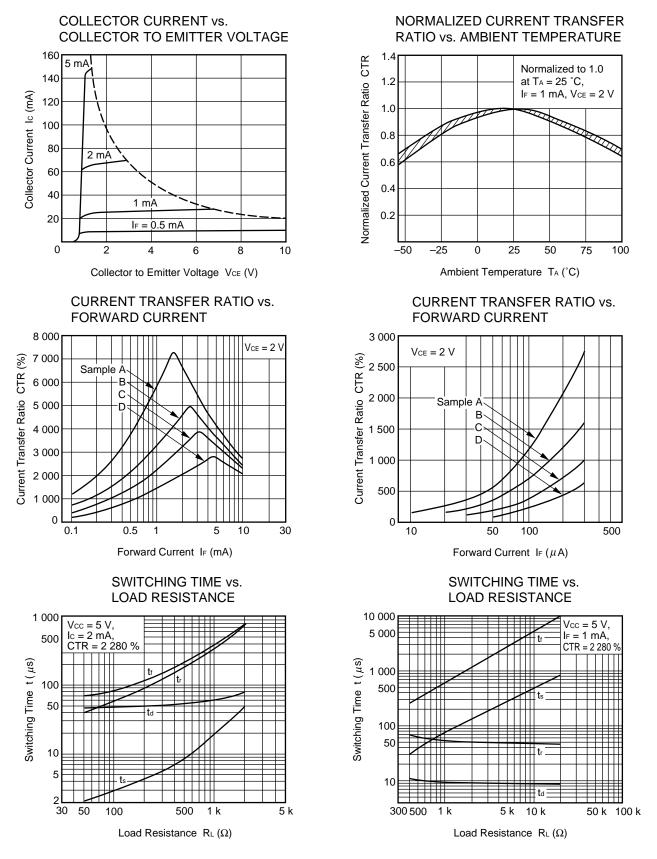




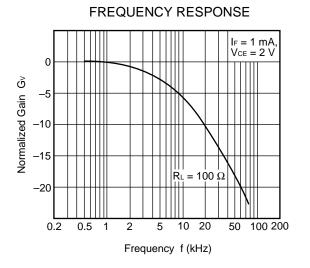


COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE

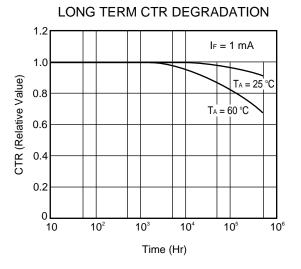




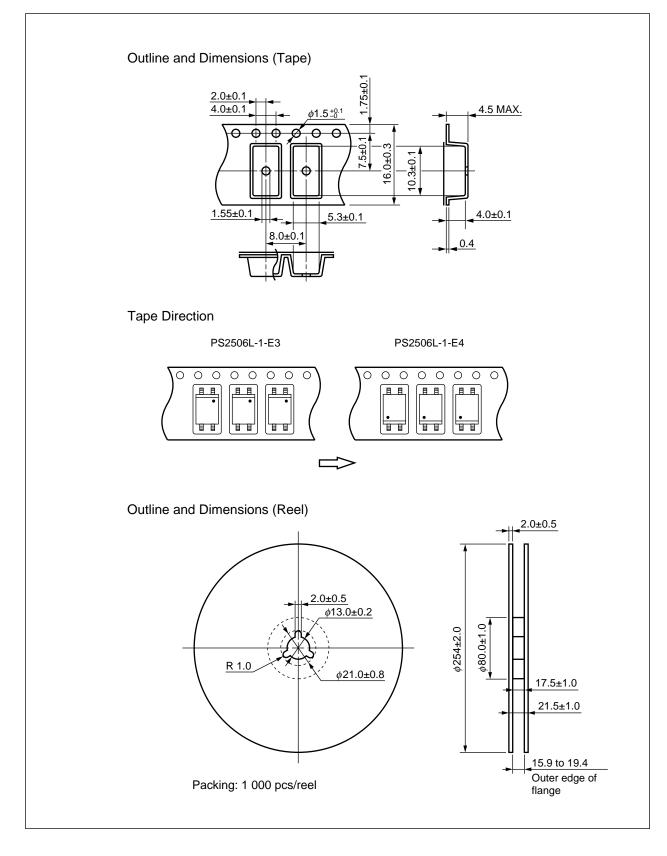
Remark The graphs indicate nominal characteristics.

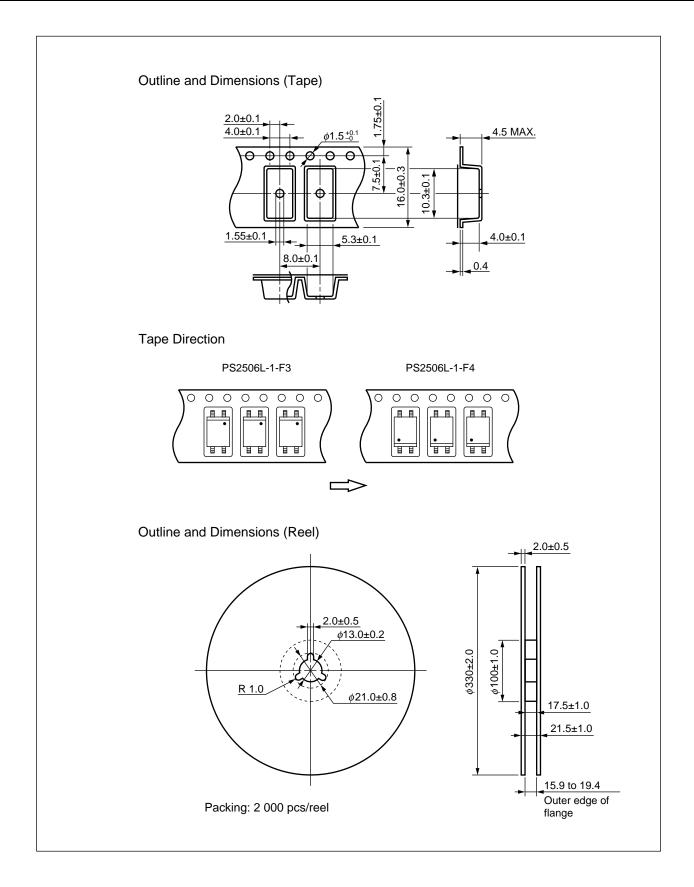


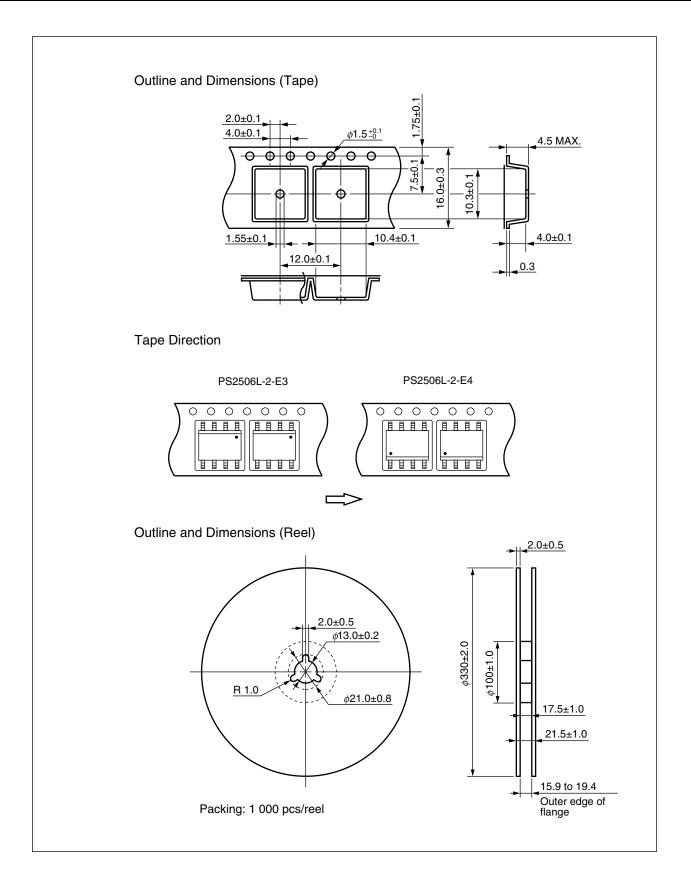




# TAPING SPECIFICATIONS (UNIT : mm)







# NOTES ON HANDLING

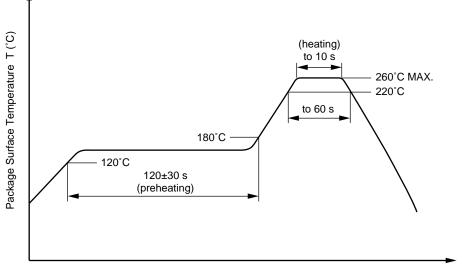
## 1. Recommended soldering conditions

## (1) Infrared reflow soldering

- Peak reflow temperature
- Time of peak reflow temperature
- Time of temperature higher than 220°C
- Time to preheat temperature from 120 to 180°C
- Number of reflows
- Flux

260°C or below (package surface temperature) 10 seconds or less 60 seconds or less 120±30 s Three Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### Recommended Temperature Profile of Infrared Reflow



Time (s)

#### (2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### ★ (3) Soldering by soldering iron

<ul> <li>Peak temperature (lead part temperature)</li> </ul>	350°C or below
Time (each pins)	3 seconds or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a
	maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100°C.

## (4) Cautions

#### • Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

## 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

## \* 3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

## USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E 00.4-0110

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	• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
	<ol> <li>Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li> </ol>
	<ol><li>Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li></ol>
	• Do not burn, destroy, cut, crush, or chemically dissolve the product.
	Do not lick the product or in any way allow it to enter the mouth.

► For further information, please contact

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## Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (\*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices	
Lead (Pb)	< 1000 PPM	-A -AZ Not Detected (*)	
Mercury	< 1000 PPM	Not Detected	
Cadmium	< 100 PPM	Not Detected	
Hexavalent Chromium	< 1000 PPM	Not Detected	
РВВ	< 1000 PPM	Not Detected	
PBDE   < 1000 PPM   Not Detection		etected	

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